

ABSTRACT

A lead frame is provided that is capable of packaging semiconductor chips with different sizes. The lead frame has a frame-shaped land; a die pad for mounting the semiconductor chip; first to fourth supporters supporting the die pad so that the die pad is located in the center of the land; and first to fourth groups of lead members formed in first to fourth trapezoidal areas, the shorter bases of which face the center of the land and the longer bases of which face the sides of the land. The first to fourth groups of lead members have first ends and second ends, the first ends being fixed to the land, and the second ends being along the shorter bases or legs of the first to fourth trapezoidal areas. The second ends are parallel in each group.